

	Type	L #	Hits	Search Text	DBs
1	BRS	L1	533	257/737.ccls.	USPAT
2	BRS	L2	455	257/738.ccls.	USPAT
3	BRS	L3	724	257/778.ccls.	USPAT
4	BRS	L4	286	257/779.ccls.	USPAT
5	BRS	L5	383	257/780.ccls.	USPAT
6	BRS	L6	193	257/772.ccls.	USPAT
7	BRS	L7	145	257/779.ccls. and solder and (ball or bump)	USPAT
8	BRS	L10	210	257/738.ccls. and solder and (ball or bump) and resin	USPAT
9	BRS	L13	207	257/737.ccls. and solder and (ball or bump) and resin	USPAT
10	BRS	L9	15	257/772.ccls. and solder and (ball or bump) and resin	USPAT
11	BRS	L14	1	257/772.ccls. and solder and (ball or bump) and resin	EPO; JPO; IBM TDB
12	BRS	L8	65	257/779.ccls. and solder and (ball or bump) and resin	USPAT
13	BRS	L15	6	257/779.ccls. and solder and (ball or bump) and resin	EPO; JPO; IBM TDB
14	BRS	L11	133	257/780.ccls. and solder and (ball or bump) and resin	USPAT
15	BRS	L16	33	257/788.ccls. and solder and (ball or bump) and resin	USPAT
16	BRS	L17	10	257/792.ccls. and solder and (ball or bump) and resin	USPAT
17	BRS	L12	264	257/778.ccls. and solder and (ball or bump) and resin	USPAT
18	BRS	L18	5	257/778.ccls. and solder and (ball or bump) and resin	EPO; JPO
19	BRS	L19	1	257/738.ccls. and solder and (ball or bump) and resin	EPO; JPO; IBM TDB

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20	BRS	L20	3	257/737.ccls. and solder and (ball or bump) and resin	EPO; JPO; IBM TDB
21	BRS	L21	617	solder and (ball or bump) and resin	EPO; JPO; IBM TDB
22	BRS	L22	0	solder and (ball or bump) and resin and meniscus	EPO; JPO; IBM TDB
23	BRS	L23	70	solder and (ball or bump) and resin and electrode and pad	EPO; JPO; IBM TDB
24	BRS	L24	581	solder and (ball or bump) and resin and electrode and pad	USPAT
25	BRS	L25	247	solder and (ball or bump) and resin and electrode and pad and paste	USPAT
26	BRS	L26	466	solder and (ball or bump) and resin and electrode and pad and (insulating or polyimide)	USPAT
27	BRS	L27	211	solder and (ball or bump) and resin and electrode and pad and (insulating or polyimide) and paste	USPAT